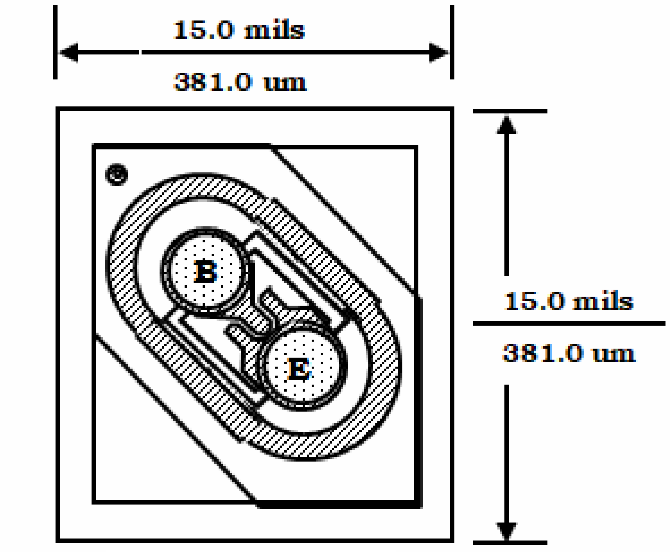
PAD LAYOUT



Bond Pads

(Emitter)	(Base)
3.6 mil Diameter	3.6 mil Diameter
91.44 um	91.44 um

NOTE

- This data is supplied for general information only and is believed to be correct at the time of publication.
- For critical applications, the customer is advised to verify device revision and pad coordinates, prior to processing
- Changes can be made without notification from the manufacturer. Die Devices cannot accept liability in that event

DEVICE	2N4209	DIE SIZE (MILS)	15 X 15
MANUFACTURER	FAIRCHILD SEMICONDUCTOR	BOND PADS MIN (MILS)	Ø 3.6
APPROVED BY	GEW	TOP METAL	Al
DATE	29/03/22	BACK METAL	Au
SERIAL NUMBER	0971	BACK POTENTIAL	COLLECTOR